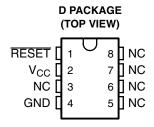
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- Power-On Reset Generator
- Automatic Reset Generation After Voltage Drop
- Low Standby Current . . . 20 μA
- RESET Output Defined When V<sub>CC</sub> Exceeds 1 V
- Precision Threshold Voltage 4.55 V ±120 mV
- High Output Sink Capability . . . 20 mA
- Comparator Hysteresis Prevents Erratic Resets

### description/ordering information

The TL7757 is a supply-voltage supervisor designed for use in microcomputer and microprocessor systems. The supervisor monitors the supply voltage for undervoltage conditions. During power up, when the supply voltage,  $V_{CC}$ , attains a value approaching 1 V, the RESET output becomes active (low) to prevent undefined operation. If the supply voltage drops below threshold voltage level ( $V_{IT-}$ ), the RESET output goes to the active (low) level until the supply undervoltage fault condition is eliminated.

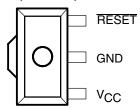


NC-No internal connection





# PK PACKAGE (TOP VIEW)



GND is in electrical contact with the tab.

### ORDERING INFORMATION

TA	PACKAG	iE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
	COIC (D)	Tube of 75	TL7757CD	77570		
	SOIC (D)	Reel of 2500	TL7757CDR	7757C T7 TL7757C		
0°C to 70°C	SOT (PK)	Reel of 1000	TL7757CPK	T7		
	T0000 / T0 00 // D)	Bulk of 1000	TL7757CLP	TI 7757C		
	TO226 / TO-92 (LP)	Reel of 2000	TL7757CLPR	1L//5/C		
	COIC (D)	Tube of 75	TL7757ID	77571		
	SOIC (D)	Reel of 2500	TL7757IDR	77571		
-40°C to 85°C	SOT (PK)	Reel of 1000	TL7757IPK	71		
	TO006 / TO 00 /LD)	Bulk of 1000	TL7757ILP	TI 77571		
	TO226 / TO-92 (LP)	Reel of 2000	TL7757ILPR	TL7757I		

<sup>&</sup>lt;sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

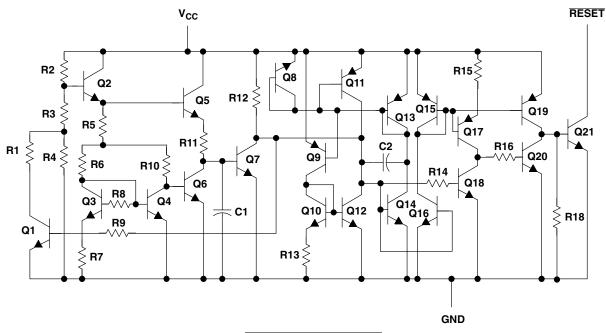


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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### equivalent schematic



ACTUAL I	
Transistors	27
Resistors	20
Capacitors	2

### absolute maximum ratings over operating junction temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub> (see Note 1)		-0.3 V to 20 V
Off-state output voltage range (see Note 1)		-0.3 V to 20 V
Output current, IO		30 mA
Package thermal impedance, $\theta_{JA}$ (see Notes 2 and 3):	D package	97°C/W
	LP package	140°C/W
	PK package	52°C/W
Operating virtual junction temperature, T <sub>J</sub>		150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10	seconds	260°C
Storage temperature range, T <sub>stg</sub>		-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values are with respect to network terminal ground.
  - 2. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
  - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



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### recommended operating conditions

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage		1	7	V
V <sub>OH</sub>	High-level output voltage			15	V
I <sub>OL</sub>	Low-level output current			20	mA
т.	Operating free-air temperature	TL7757C	0	0 70	
T <sub>A</sub>	Operating nee-an temperature	TL7757I	-40	85	- °C

### electrical characteristics at specified free-air temperature

	PARAMETER	TEST CONDITIONS	_	Т	L7757C		
	PARAMETER	TEST CONDITIONS	T <sub>A</sub>	MIN	TYP	MAX	UNII
.,	No matice and in a large of the cook and cooks are at M		25°C	4.43	4.55	4.67	V
$V_{IT-}$	Negative-going input threshold voltage at $V_{CC}$		0°C to 70°C	4.4		4.7	V
\/ +	I historia at V		25°C	40	50	60	\/
V <sub>hys</sub> †	Hysteresis at V <sub>CC</sub>		0°C to 70°C	30		70	V mV V μA V
.,	Landard and and and and	1 00 m A 1/ 4 0 1/	25°C		0.4	8.0	
V <sub>OL</sub>	Low-level output voltage	$I_{OL} = 20 \text{ mA},  V_{CC} = 4.3 \text{ V}$	0°C to 70°C			8.0	V
	High lavel autout august	$V_{CC} = 7 \text{ V}, \qquad V_{OH} = 15 \text{ V},$	25°C			1	
Іон	High-level output current	See Figure 1	0°C to 70°C			1	μΑ
\/ +	Danier in was at walters	$R_L = 2.2 \text{ k}\Omega$	25°C		0.8	1	V
V <sub>res</sub> ‡	Power-up reset voltage	$V_{CC}$ slew rate $\leq 5 \text{ V/}\mu\text{s}$	0°C to 70°C			1.2	V
		V 40V	25°C		1400	2000	
Icc	Supply current	V <sub>CC</sub> = 4.3 V	0°C to 70°C			2000	μΑ
		V <sub>CC</sub> = 5.5 V	0°C to 70°C			40	

<sup>†</sup> This is the difference between positive-going input threshold voltage, V<sub>IT+</sub>, and negative-going input threshold voltage, V<sub>IT-</sub>. ‡ This is the lowest voltage at which RESET becomes active.

### switching characteristics at specified free-air temperature

	PARAMETER	TEST CONDITIONS	_	Т			
	PARAMETER	1EST CONDITIONS	T <sub>A</sub>	MIN	TYP	MAX	UNIT
	Propagation delay time, low-to-high-level	$V_{CC}$ slew rate $\leq 5 \text{ V/}\mu\text{s}$ ,	25°C		3.4	5	
t <sub>PLH</sub>	output	See Figures 2 and 3	0°C to 70°C			5	μs
	Propagation delay time, high-to-low-level	0 5	25°C		2	5	_
t <sub>PHL</sub>	output	See Figures 2 and 3	0°C to 70°C			5	μs
	Disastina	V <sub>CC</sub> slew rate ≤ 5 V/μs,	25°C		0.4	1	_
t <sub>r</sub>	Rise time	See Figures 2 and 3	0°C to 70°C				μs
	E-H-Co.	0 5	25°C		0.05	1	_
t <sub>f</sub>	Fall time	See Figures 2 and 3	0°C to 70°C			1	μs
	Minimum pulse duration at V <sub>CC</sub> for output		25°C			5	
t <sub>w(min)</sub>	response		0°C to 70°C			5	μs

### TL7757 SUPPLY-VOLTAGE SUPERVISOR AND PRECISION VOLTAGE DETECTOR

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### electrical characteristics at specified free-air temperature

	PARAMETER	TEST CONDITIONS	_	7	UNIT		
	PANAME I EN	TEST CONDITIONS	T <sub>A</sub>	MIN	TYP	MAX	UNII
,,	No notice as in a forest three should sell a set V		25°C	4.43	4.55	4.67	.,
$V_{IT-}$	Negative-going input threshold voltage at V <sub>CC</sub>		-40°C to 85°C	4.4		4.7	٧
v +	Heatensia at V	250		40	50	60	\/
V <sub>hys</sub> †	Hysteresis at V <sub>CC</sub>		-40°C to 85°C	30		70	mV
,,	Law L	1 00 m A 1/ 4 0 1/	25°C		0.4	0.8	V
V <sub>OL</sub>	Low-level output voltage	$I_{OL} = 20 \text{ mA},  V_{CC} = 4.3 \text{ V}$	-40°C to 85°C			8.0	V
Ī.	I limb land a short a summer	$V_{CC} = 7 \text{ V}, \qquad V_{OH} = 15 \text{ V},$	25°C			1	
Іон	High-level output current	See Figure 1	-40°C to 85°C			1	μΑ
+	D	$R_L = 2.2 \text{ k}\Omega$ ,	25°C		0.8	1	V
V <sub>res</sub> ‡	Power-up reset voltage	$V_{CC}$ slew rate $\leq 5 \text{ V/}\mu\text{s}$	-40°C to 85°C			1.2	٧
		V 40V	25°C		1400	2000	
Icc	Supply current	$V_{CC} = 4.3 \text{ V}$	-40°C to 85°C			2100	μΑ
		V <sub>CC</sub> = 5.5 V	-40°C to 85°C			40	

<sup>†</sup> This is the difference between positive-going input threshold voltage, V<sub>IT+</sub>, and negative-going input threshold voltage, V<sub>IT-</sub>.

### switching characteristics at specified free-air temperature

	PARAMETER	TEST CONDITIONS	_	7			
	PARAMETER	TEST CONDITIONS	T <sub>A</sub>	MIN	TYP	MAX	UNIT
	Duran a matical adalas, times a lass, to brigh lassed a status	$V_{CC}$ slew rate $\leq 5 \text{ V/}\mu\text{s}$ ,	25°C		3.4	5	
t <sub>PLH</sub>	Propagation delay time, low-to-high-level output	See Figures 2 and 3	-40°C to 85°C			5	μS
	Donor and the delegation of the test of th	0 5	25°C		2	5	
t <sub>PHL</sub>	Propagation delay time, high-to-low-level output	See Figures 2 and 3	-40°C to 85°C			5	μs
	Disa Nova	V <sub>CC</sub> slew rate ≤ 5 V/μs,	25°C		0.4	1	
t <sub>r</sub>	Rise time	See Figures 2 and 3	-40°C to 85°C			1	μs
	E 11.1	0 5 0 10	25°C		0.05	1	
t <sub>f</sub>	Fall time	See Figures 2 and 3	-40°C to 85°C			1	μs
•	Minimum pulse duration at V <sub>CC</sub> for output		25°C			5	
t <sub>w(min)</sub>	response		-40°C to 85°C			5	μs

<sup>&</sup>lt;sup>‡</sup> This is the lowest voltage at which RESET becomes active.

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### PARAMETER MEASUREMENT INFORMATION

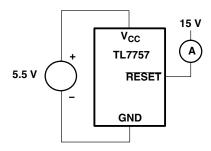
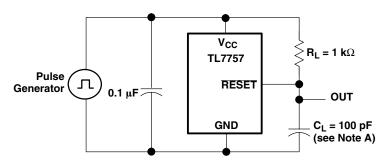


Figure 1. Test Circuit for Output Leakage Current



NOTE A: Includes jig and probe capacitance

Figure 2. Test Circuit for RESET Output Switching Characteristics

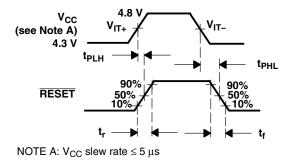


Figure 3. Switching Diagram

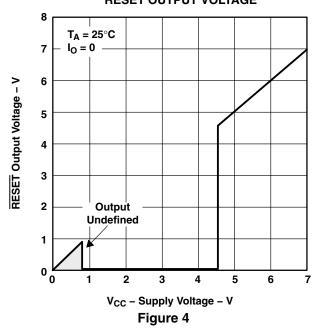


### TYPICAL CHARACTERISTICS†

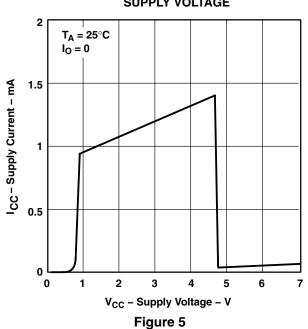
### **Table of Graphs**

		FIGURE
V <sub>CC</sub>	Supply voltage vs RESET output voltage	4
I <sub>CC</sub>	Supply current vs Supply voltage	5
I <sub>CC</sub>	Supply current vs Free-air temperature	6
V <sub>OL</sub>	Low-level output voltage vs Low-level output current	7
V <sub>OL</sub>	Low-level output voltage vs Free-air temperature	8
I <sub>OL</sub>	Output current vs Supply voltage	9
V <sub>IT-</sub>	Input threshold voltage (negative-going $V_{\text{CC}}$ ) vs Free-air temperature	10
V <sub>res</sub>	Power-up reset voltage vs Free-air temperature	11
V <sub>res</sub>	Power-up reset voltage and supply voltage vs Time	12
	Propagation delay time	13

# SUPPLY VOLTAGE vs RESET OUTPUT VOLTAGE



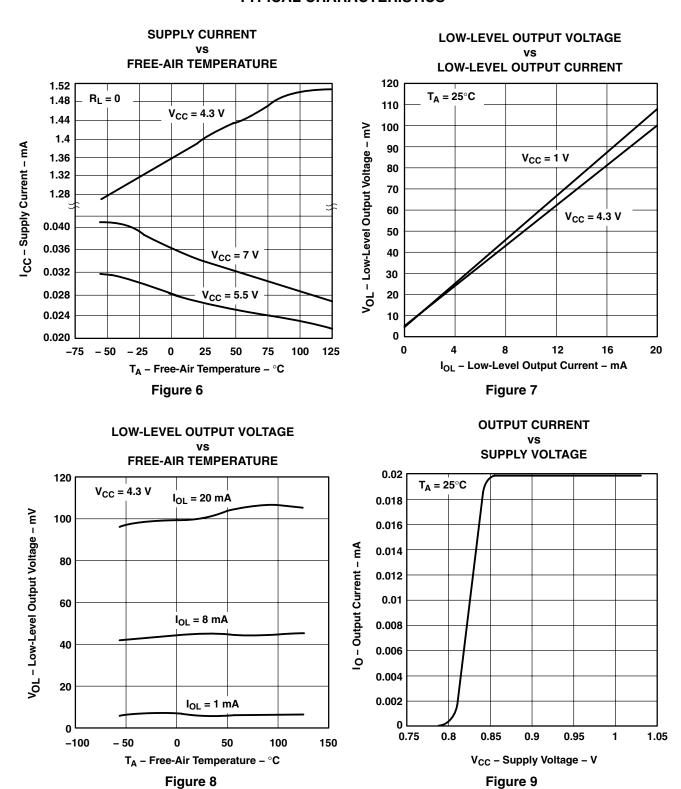
### SUPPLY CURRENT vs SUPPLY VOLTAGE



<sup>†</sup> Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



### TYPICAL CHARACTERISTICS†



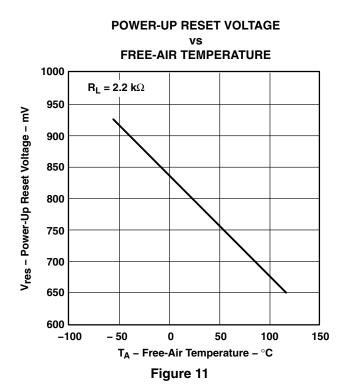
<sup>†</sup> Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



### TYPICAL CHARACTERISTICS†

### (NEGATIVE-GOING V<sub>CC</sub>) FREE-AIR TEMPERATURE 4.6 $R_L = 0$ 4.59 V<sub>IT</sub> - Input Threshold Voltage - V 4.58 4.57 4.56 4.55 4.54 4.53 4.52 4.51 4.5 -100 150 T<sub>A</sub> - Free-Air Temperature - °C

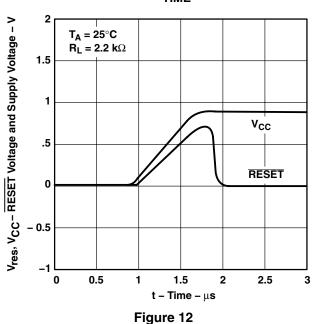
**INPUT THRESHOLD VOLTAGE** 



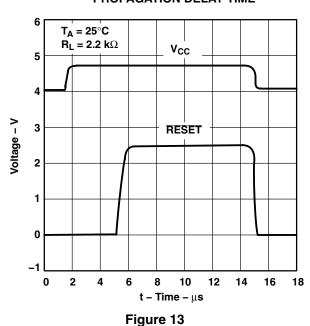
# POWER-UP RESET VOLTAGE AND SUPPLY VOLTAGE

Figure 10

vs TIME



### PROPAGATION DELAY TIME

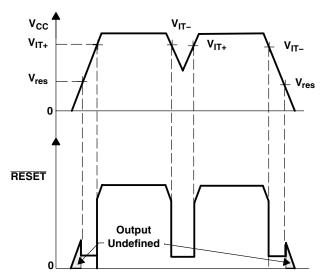


<sup>†</sup> Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

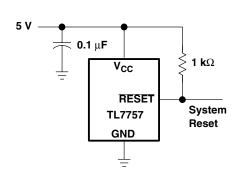


### **APPLICATION INFORMATION**

### **TYPICAL TIMING DIAGRAM**



### **TYPICAL APPLICATION DIAGRAM**







6-Feb-2020

### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TL7757CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	7757C	Samples
TL7757CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	7757C	Samples
TL7757CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	7757C	Samples
TL7757CLP	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	SN	N / A for Pkg Type	0 to 70	TL7757C	Samples
TL7757CLPE3	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	SN	N / A for Pkg Type	0 to 70	TL7757C	Samples
TL7757CLPR	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	SN	N / A for Pkg Type	0 to 70	TL7757C	Samples
TL7757CPK	ACTIVE	SOT-89	PK	3	1000	Green (RoHS & no Sb/Br)	SN	Level-2-260C-1 YEAR	0 to 70	Т7	Samples
TL7757CPKG3	ACTIVE	SOT-89	PK	3	1000	Green (RoHS & no Sb/Br)	SN	Level-2-260C-1 YEAR	0 to 70	Т7	Samples
TL7757ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	77571	Samples
TL7757IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	77571	Samples
TL7757ILP	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	SN	N / A for Pkg Type	-40 to 85	TL7757I	Samples
TL7757ILPE3	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	SN	N / A for Pkg Type	-40 to 85	TL7757I	Samples
TL7757ILPR	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	SN	N / A for Pkg Type	-40 to 85	TL7757I	Samples
TL7757IPK	ACTIVE	SOT-89	PK	3	1000	Green (RoHS & no Sb/Br)	SN	Level-2-260C-1 YEAR	-40 to 85	71	Samples
TL7757IPKG3	ACTIVE	SOT-89	PK	3	1000	Green (RoHS & no Sb/Br)	SN	Level-2-260C-1 YEAR	-40 to 85	71	Samples

<sup>(1)</sup> The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.



### PACKAGE OPTION ADDENDUM

6-Feb-2020

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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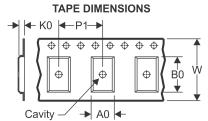
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**PACKAGE MATERIALS INFORMATION** 

www.ti.com 24-Apr-2020

### TAPE AND REEL INFORMATION





Α0	
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



### \*All dimensions are nominal

All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL7757CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL7757CPK	SOT-89	PK	3	1000	180.0	12.4	4.91	4.52	1.9	8.0	12.0	Q3
TL7757IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL7757IPK	SOT-89	PK	3	1000	180.0	12.4	4.91	4.52	1.9	8.0	12.0	Q3

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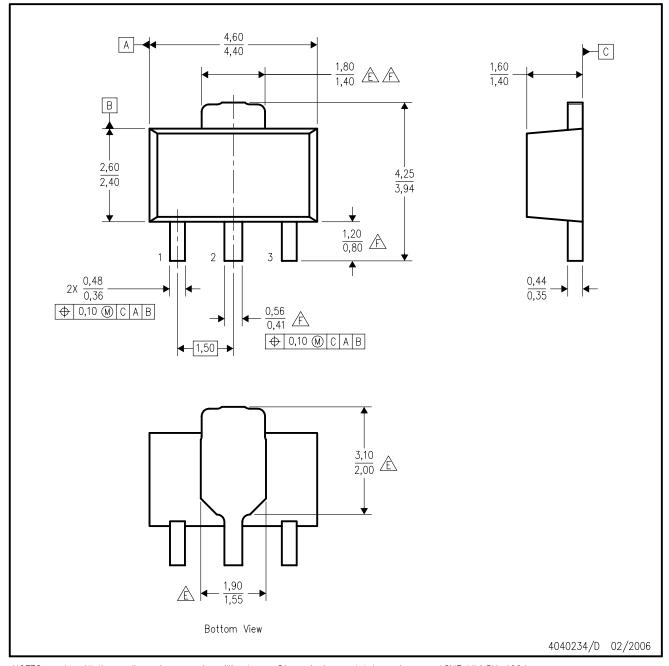


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL7757CDR	SOIC	D	8	2500	340.5	338.1	20.6
TL7757CPK	SOT-89	PK	3	1000	340.0	340.0	38.0
TL7757IDR	SOIC	D	8	2500	340.5	338.1	20.6
TL7757IPK	SOT-89	PK	3	1000	340.0	340.0	38.0

### PK (R-PSSO-F3)

### PLASTIC SINGLE-IN-LINE PACKAGE

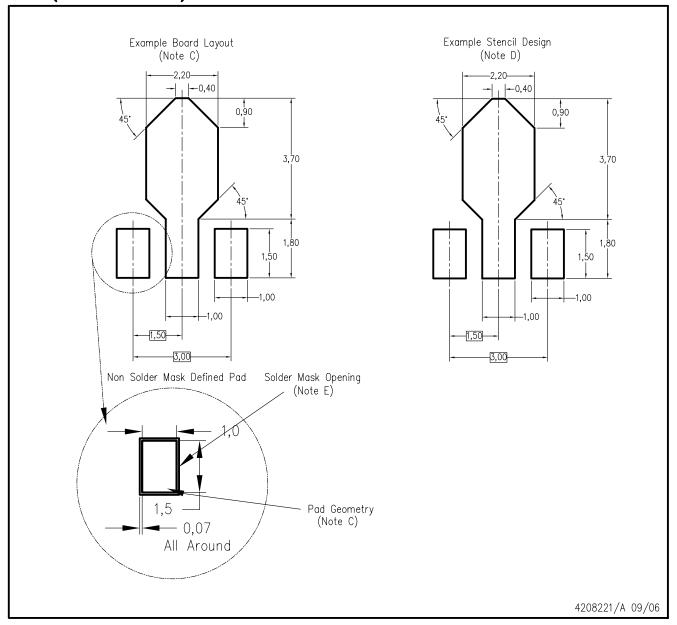


NOTES:

- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
- This drawing is subject to change without notice.
- The center lead is in electrical contact with the tab.
- Body dimensions do not include mold flash or protrusion. Mold flash and protrusion not to exceed 0.15 per side.
- Thermal pad contour optional within these dimensions.
- Falls within JEDEC T0-243 variation AA, except minimum lead length, pin 2 minimum lead width, minimum tab width.



## PK (R-PDSO-G3)



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





SMALL OUTLINE INTEGRATED CIRCUIT



### NOTES:

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



### NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.





Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040001-2/F



TO-92 - 5.34 mm max height

TO-92



### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.
- 3. Lead dimensions are not controlled within this area.4. Reference JEDEC TO-226, variation AA.
- 5. Shipping method:

  - a. Straight lead option available in bulk pack only.
     b. Formed lead option available in tape and reel or ammo pack.
  - c. Specific products can be offered in limited combinations of shipping medium and lead options.
  - d. Consult product folder for more information on available options.



TO-92





TO-92





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